

ABSTRACT

A first electronic component 6 is connected and fixed onto a first electrode pattern 4 with a conductive bonding material 7, the first electrode pattern 4 being provided on a first supporting layer 12. A second supporting layer 13 including a second electrode pattern 5 is press-bonded onto the electronic component-fixed surface of the first supporting layer 12 with a first prepreg 2 therebetween to perform transfer. Then, the first supporting layer 12 and the second supporting layer 13 are separated from the first prepreg 2. After separation, the first prepreg 2 is cured. A second electronic component 8 is connected and fixed onto the back surface of the second electrode pattern 5 with a conductive bonding material 9. A third supporting layer 14 including a third electrode pattern 3 is press-bonded onto the second electronic component-fixed surface with a second prepreg 1 therebetween to perform transfer. Then, the third supporting layer 14 is separated from the second prepreg 1, and the second prepreg 1 is cured. In this way, the prepreps 1 and 2 and electrode patterns 3, 4, and 5 are sequentially laminated, thereby reducing the connection resistance between laminated electrode patterns or between an electrode pattern and an electronic component. Consequently, a component-embedded substrate A having high connection reliability is obtained.